





BOXOGEO

20V NPN SILICON PLANAR MEDIUM POWER TRANSISTOR IN SOT89

Features

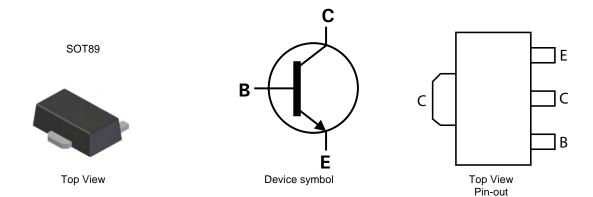
- BV_{CEO} > 20V
- High current capability Maximum Continuous Current I_C = 1A
- Low saturation voltage V_{CE(sat)} < 500mV @ 1A
- Complementary PNP type: BCX69
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free, "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT89
- · Case Material: Molded Plastic, "Green" Molding Compound
- Moisture Sensitivity: Level 1 per J-STD-020
- UL Flammability Rating 94V-0
- Terminals: Matte Tin Finish
- Weight: 0.052 grams (Approximate)

Application

- Power MOSFET gate driving
- Low loss power switching



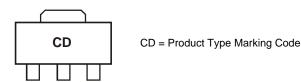
Ordering Information (Notes 3 & 4)

Product	Status	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
BCX6825TA	Commercial	CD	7	12	1000
BCX6825QTA	Automotive	CD	7	12	1000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For packaging details, go to our website at http://www.diodes.com
- 4. Products with Q-suffix are automotive grade. Automotive products are electrical and thermal the same as the commercial, except where specified.

Marking Information





Maximum Ratings @T_A = 25°C unless otherwise specified

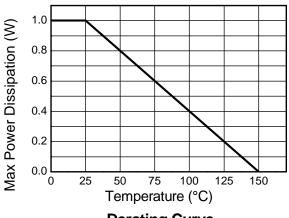
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	25	V
Collector-Emitter Voltage	V _{CEO}	20	V
Emitter-Base Voltage	V_{EBO}	5	V
Continuous Collector Current	Ic	1	Α
Peak Pulse Current	I _{CM}	2	Α

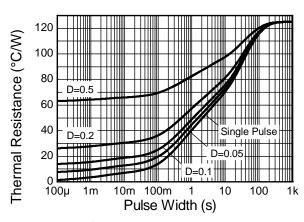
Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector Power Dissipation	P _D	1	W
Thermal Resistance, Junction to Ambient Air (Note 5)	$R_{\theta JA}$	125	°C/W
Thermal Resistance, Junction to Leads (Note 6)	$R_{\theta JL}$	10.01	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-65 to +150	°C

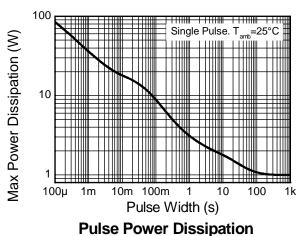
Notes: 5. For the device mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions. 6. Thermal resistance from junction to solder-point (on the exposed collector pad).

Thermal Characteristics

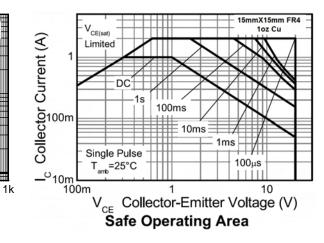




Derating Curve



Transient Thermal Impedance



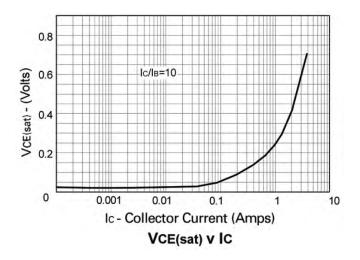


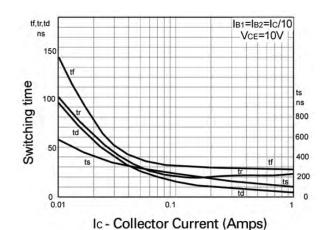
Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур.	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_CBO	25	-	-	V	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage (Note 7)	BV _{CEO}	20	-	-	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	BV_{EBO}	5	-	-	V	$I_E = 100\mu A$
Collector Cutoff Current	I _{CBO}	-	-	100 10	nΑ μΑ	V _{CB} = 25V V _{CB} = 25V, T _A = 125°C
Emitter Cutoff Current	I _{EBO}	-	-	10	μA	$V_{EB} = 5V$
DC current transfer Static ratio (Note 7)	h _{FE}	50 160 60	- 250 -	- 400 -	-	$I_{C} = 5mA, V_{CE} = 10V$ $I_{C} = 500mA, V_{CE} = 1V$ $I_{C} = 1A, V_{CE} = 1V$
Collector-Emitter Saturation Voltage (Note 7)	V _{CE(sat)}	-	-	0.5	V	$I_C = 1A$, $I_B = 100mA$
Base-Emitter Turn-on Voltage (Note 7)	V _{BE(on)}	-	ı	1.0	V	$I_C = 1A$, $V_{CE} = 1V$
Transitional Frequency	f _T	100	-	-	MHz	$I_C = 100 \text{mA}, V_{CE} = 5 \text{V}$ f = 100MHz
Output capacitance	C_{obo}	-	-	25	pF	$V_{CB} = 10V$, $f = 1MHz$

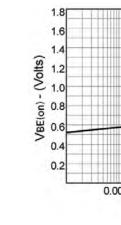
Notes:

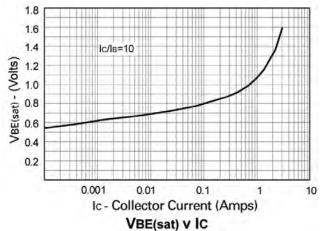
Typical Characteristics





Switching Speeds

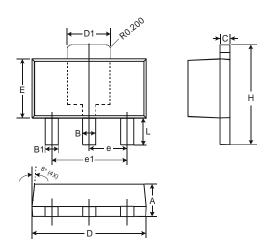




^{7.} Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤2%.

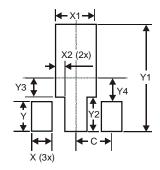


Package Outline Dimensions



SOT89			
Dim	Min	Max	
Α	1.40	1.60	
В	0.44	0.62	
B1	0.35	0.54	
С	0.35	0.43	
D	4.40	4.60	
D1	1.52	1.83	
Е	2.29	2.60	
е	1.50 Typ		
e1	3.00 Typ		
Н	3.94	4.25	
L	0.89	1.20	
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Х	0.900
X1	1.733
X2	0.416
Υ	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500





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